Quad Type D Flip-Flop

The MC14175B quad type D flip-flop is constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. Each of the four flip-flops is positive-edge triggered by a common clock input (C). An active-low reset input (R) asynchronously resets all flip-flops. Each flip-flop has independent Data (D) inputs and complementary outputs (Q and Q). These devices may be used as shift register elements or as type T flip-flops for counter and toggle applications.

Features

- Complementary Outputs
- Static Operation
- All Inputs and Outputs Buffered
- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Output Compatible with Two Low-Power TTL Loads or One Low-Power Schottky TTL Load
- Functional Equivalent to TTL 74175
- These Devices are Pb-Free and are RoHS Compliant
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

· -	00,		
Parameter	Symbol	Value	Unit
DC Supply Voltage Range	V_{DD}	-0.5 to +18.0	V
Input or Output Voltage Range (DC or Transient)	V _{in} , V _{out}	-0.5 to V _{DD} + 0.5	٧
Input or Output Current (DC or Transient) per Pin	I _{in} , I _{out}	±10	mA
Power Dissipation per Package (Note 1)	P _D	500	mW
Ambient Temperature Range	T _A	-55 to +125	°C
Storage Temperature Range		-65 to +150	°C
Lead Temperature (8-Second Soldering)		260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

 Temperature Derating: Plastic "P and D/DW" Packages: – 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



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MARKING DIAGRAMS



PDIP-16 P SUFFIX CASE 648 16<mark> ለተለተለተ</mark> MC14175BCP O AWLYYWWG 1 የየተመመመመ



SOIC-16 D SUFFIX CASE 751B 

SOEIAJ-16 F SUFFIX CASE 966 A = Assembly Location

WL, L = Wafer Lot
 YY, Y = Year
 WW, W = Work Week
 G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
MC14175BCPG	PDIP-16 (Pb-Free)	500 Units/Rail
MC14175BDG	SOIC-16 (Pb-Free)	48 Units/Rail
MC14175BDR2G	SOIC-16 (Pb-Free)	2500/Tape & Reel
NLV14175BDR2G	SOIC-16 (Pb-Free)	2500/Tape & Reel
MC14175BFELG	SOEIAJ-16 (Pb-Free)	2000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

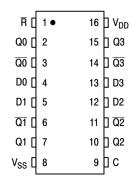


Figure 1. Pin Assignment

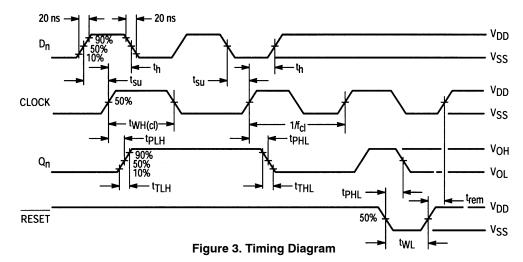
CLOCK 90-Q0 **-0** 2 Q0 **-0** 3 10-RESET Q1 40-D0 Q1 **-0** 6 Q2 **-0** 10 5 **0**-D1 Q2 **-**0 11 12 O-**-0** 15 Q3 Q3 13 0-D3 **-**0 14 $V_{DD} = PIN 16$ V_{SS} = PIN 8

Figure 2. Block Diagram

TRUTH TABLE

	Inputs			Outputs	
Clock	Data	Reset	Q	Q	
_	0	1	0	1	
_	1	1	1	0	No
_	X	1	Q	Q	No Change
Х	Х	0	0	1	Change

X = Don't Care



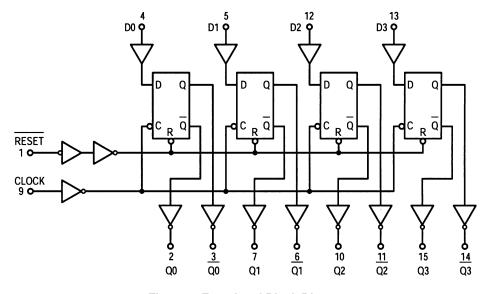


Figure 4. Functional Block Diagram

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

			- 5	5°C		25°C		125	5°C	
Characteristic	Symbol	V _{DD} Vdc	Min	Max	Min	Typ (Note 2)	Max	Min	Max	Unit
Output Voltage "0" Level $V_{in} = V_{DD}$ or 0	V _{OL}	5.0 10 15	- - -	0.05 0.05 0.05	- - -	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
V _{in} = 0 or V _{DD} "1" Level	V _{OH}	5.0 10 15	4.95 9.95 14.95	- - -	4.95 9.95 14.95	5.0 10 15	- - -	4.95 9.95 14.95	- - -	Vdc
Input Voltage "0" Level $(V_O = 4.5 \text{ or } 0.5 \text{ Vdc})$ $(V_O = 9.0 \text{ or } 1.0 \text{ Vdc})$ $(V_O = 13.5 \text{ or } 1.5 \text{ Vdc})$	V _{IL}	5.0 10 15	- - -	1.5 3.0 4.0	- - -	2.25 4.50 6.75	1.5 3.0 4.0	- - -	1.5 3.0 4.0	Vdc
"1" Level $(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	V _{IH}	5.0 10 15	3.5 7.0 11	- - -	3.5 7.0 11	2.75 5.50 8.25	1 1 1	3.5 7.0 11	- - -	Vdc
	Іон	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	- - -	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	1 1 1	- 1.7 - 0.36 - 0.9 - 2.4	- - -	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ Sink $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	I _{OL}	5.0 10 15	0.64 1.6 4.2	- - -	0.51 1.3 3.4	0.88 2.25 8.8	- - -	0.36 0.9 2.4	- - -	mAdc
Input Current	I _{in}	15	_	± 0.1	_	±0.00001	± 0.1	-	± 1.0	μAdc
Input Capacitance (V _{in} = 0)	C _{in}	_	_	-	_	5.0	7.5	_	_	pF
Quiescent Current (Per Package)	I _{DD}	5.0 10 15	- - -	5.0 10 20	- - -	0.005 0.010 0.015	5.0 10 20	- - -	150 300 600	μAdc
Total Supply Current (Note 3, 4) (Dynamic plus Quiescent, Per Package) (C _L = 50 pF on all outputs, all buffers switching)	I _T	5.0 10 15			$I_T = (3)$	I.7 μA/kHz) f 3.4 μA/kHz) f 5.0 μA/kHz) f	+ I _{DD}			μAdc

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF: I_T(C_L) = I_T(50 pF) + (C_L – 50) Vfk where: I_T is in μA (per package), C_L in pF, V = (V_{DD} – V_{SS}) in volts, f in kHz is input frequency, and k = 0.004.

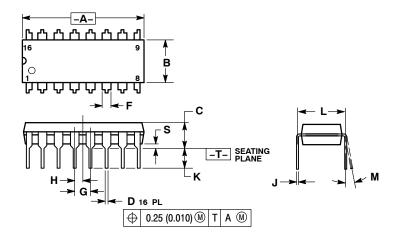
SWITCHING CHARACTERISTICS (Note 5) (C_L = 50 pF, T_A = 25°C)

					All Types			
Characteristic	Symbol	V _{DD} Vdc	Min	Typ (Note 6)	Max	Unit		
Output Rise and Fall Time $ \begin{aligned} t_{TLH}, t_{THL} &= (1.35 \text{ ns/pF}) C_L + 32 \text{ ns} \\ t_{TLH}, t_{THL} &= (0.6 \text{ ns/pF}) C_L + 20 \text{ ns} \\ t_{TLH}, t_{THL} &= (0.4 \text{ ns/pF}) C_L + 20 \text{ ns} \end{aligned} $	t _{TLH} , t _{THL}	5.0 10 15	- - -	100 50 40	200 100 80	ns		
Propagation Delay Time — Clock to Q, Q t_{PLH} , t_{PHL} = (0.9 ns/pF) C_L + 175 ns t_{PLH} , t_{PHL} = (0.36 ns/pF) C_L + 72 ns t_{PLH} , t_{PHL} = (0.26 ns/pF) C_L + 57 ns	t _{РІН} , t _{РНІ}	5.0 10 15	- - -	220 90 70	400 160 120	ns		
Propagation Delay Time — Reset to Q, Q t_{PHL} = (0.9 ns/pF) C_L + 280 ns t_{PHL} = (0.36 ns/pF) C_L + 112 ns t_{PHL} = (0.26 ns/pF) C_L + 87 ns	t _{PHL} , t _{PLH}	5.0 10 15	- - -	325 130 100	500 200 150	ns		
Clock Pulse Width	t _{WH}	5.0 10 15	250 100 75	110 45 35	- - -	ns		
Reset Pulse Width	t _{WL}	5.0 10 15	200 80 60	100 40 30	- - -	ns		
Clock Pulse Frequency	f _{cl}	5.0 10 15	- - -	4.5 11 14	2.0 5.0 6.5	mHz		
Clock Pulse Rise and Fall Time	t _{TLH} , t _{THL}	5.0 10 15	- - -	- - -	15 5.0 4.0	μs		
Data Setup Time	t _{su}	5.0 10 15	120 50 40	60 25 20	- - -	ns		
Data Hold Time	th	5.0 10 15	80 40 30	40 20 15	- - -	ns		
Reset Removal Time	t _{rem}	5.0 10 15	250 100 80	125 50 40	- - -	ns		

^{5.} The formulas given are for the typical characteristics only at 25°C.
6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

PACKAGE DIMENSIONS

PDIP-16 CASE 648-08 **ISSUE T**



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

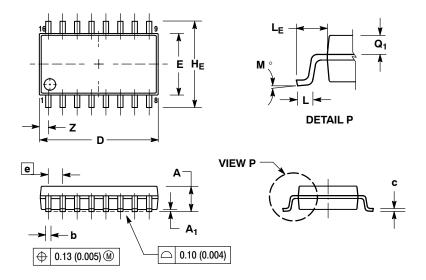
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

 4. DIMENSION B DOES NOT INCLUDE

- MOLD FLASH.
 ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100	BSC	2.54	BSC
Н	0.050	BSC	1.27	BSC
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10 °	0°	10 °
S	0.020	0.040	0.51	1.01

SOEIAJ-16 CASE 966-01 **ISSUE A**



- 11ES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
 Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS D AND E DO NOT INCLUDE
 MOLD FLASH OR PROTRUSIONS AND ARE
 MEASURED AT THE PARTING LINE. MOLD FLASH
 OR PROTRUSIONS SHALL NOT EXCEED 0.15
 (0.006) PER SIDE.
 4. TERMINAL IN LIMBERS ARE SHOWN FOR
- (0.006) PER SIDE.

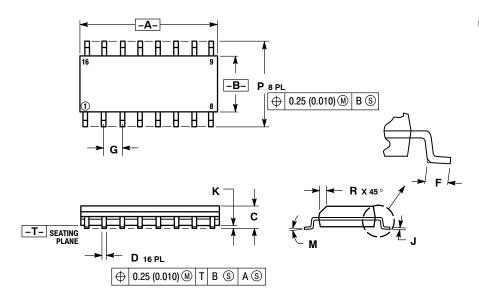
 4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	,	,		
	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
е	1.27	1.27 BSC		BSC
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10°
Q ₁	0.70	0.90	0.028	0.035
7		0.78		0.031

PACKAGE DIMENSIONS

SOIC-16 CASE 751B-05 ISSUE K

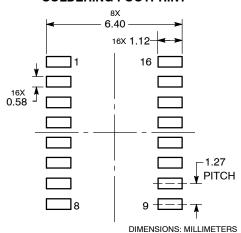


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
ם	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
7	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

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